

## Parker Chomerics CHO-BOND® 1121 General Purpose Adhesive-Sealant Silver Silicone

Category : Polymer , Thermoset , Silicone

### Material Notes:

Description: Xylene-free version of CHO-BOND 1038; rec. bond line thickness: > 0.18 mm; primer promotes adhesion CHO-BOND® 1121 is an electrically conductive, one-component silicone adhesive-sealant that may be used for bonding EMI gaskets or for providing EMI and environmental protection as a caulk. This material cures on exposure to atmospheric moisture and contains no acetic acid or other corrosive agents. Cured CHO-BOND 1121 remains flexible and conductive at temperatures from -55°C to 125°C. Uncured CHO-BOND 1038 is a smooth, nonflowing paste that may be knife-spread or applied directly to a vertical surface. CHO-BOND 1121 forms a cured skin within two minutes after exposure to atmospheric moisture and therefore must be tooled within this time period. A full cure is obtained after room temperature aging at 50% relative humidity for one week. In many cases, a good set is obtained within 8 hours. Priming the substrate with CHO-BOND 1086 is recommended. Typical Applications: Sealing enclosure seams; airframe gap sealing; connector shielding. Information provided by Chomerics

Order this product through the following link:

[http://www.lookpolymers.com/polymer\\_Parker-Chomerics-CHO-BOND-1121-General-Purpose-Adhesive-Sealant-Silver-Silicone.php](http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-1121-General-Purpose-Adhesive-Sealant-Silver-Silicone.php)

Physical Properties	Metric	English	Comments
Specific Gravity	3.60 g/cc	3.60 g/cc	
Volatile Organic Compounds (VOC) Content	0.00 g/l	0.00 g/l	
Thickness	178 microns	7.01 mil	

Mechanical Properties	Metric	English	Comments
Shear Strength	>= 1.03 MPa	>= 149 psi	Lap

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.010 ohm-cm	<= 0.010 ohm-cm	

Processing Properties	Metric	English	Comments
Cure Time	10100 min @Temperature 24.0 °C	168 hour @Temperature 75.2 °F	
Shelf Life	12.0 Month	12.0 Month	

Descriptive Properties	Value	Comments
Filler	Ag/Cu	
Resin System	Silicone	

Descriptive Properties	Value	Comments
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## Contact Songhan Plastic Technology Co.,Ltd.

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